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**KEATING & BENNETT LLP**

# Fax

2834

<b>To:</b> Examiner J. Gonzalez	<b>From:</b> Christopher A. Bennett
<b>Fax:</b> 703-872-9319	<b>Date:</b> February 27, 2003
<b>Phone:</b> 703-305-1563	<b>Pages:</b> 17
<b>Re:</b> 09/656,106 36856.345	<b>CC:</b>

**•Comments:**

Examiner Gonzalez,

Please find attached the following documents for U.S. Application No. 09/656,106:


1. Amendment After Final Rejection;
2. Petition for 2-month extension of time;
3. Credit card form in the amount of \$410.00;
4. Notice of Appeal (2 copies); and
5. Credit card form in the amount of \$320.00.

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FEB 27 2003

TECHNOLOGY CENTER 2800

Respectfully submitted




Christopher A. Bennett  
for  
KEATING & BENNETT, LLP  
(Reg. No. 46,710)

**RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP ART UNIT 2834****CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being transmitted to Group Art Unit 2834, 703-872-9319, addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: February 27, 2003

  
Sonia V. McVean

**PATENT  
36856.345**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Masaya WAJIMA et al.	Art Unit: 2834
Serial No.: 09/656,106	Examiner: J. Gonzalez
Filed: September 6, 2000	
Title: CHIP ELECTRONIC COMPONENT AND MOUNTING STRUCTURE FOR THE SAME	

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**AMENDMENT AFTER FINAL REJECTION**

**TECHNOLOGY CENTER 2800**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated October 23, 2002, the period for response to which has been extended to March 23, 2003, by the accompanying Petition for a TWO-month Extension of Time, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please REPLACE claim 14 with the following claim:

14. (Twice amended) A chip electronic component comprising:

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a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;

an electronic component element having electrodes and defining part of said body of the chip electronic component; and

a plurality of external electrodes arranged so as to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element;

wherein each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is arranged to have an almost uniform width from one longitudinal end to the other, and satisfy the relation  $L_1 < L_3$ , where  $L_3$  is the width of each portion of the external electrodes provided on the lower surface of said body of the chip electronic component, and  $L_1$  is the width of each portion of the external electrodes provided on the at least one side surface of said body of the chip electronic component, each of the widths  $L_1$  and  $L_3$  being defined as a dimension of the external electrodes measured in a longitudinal direction of the body of the chip electronic component.